



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 59457
Application ID: 10761122
Title of Invention: SOLVENT FREE PHOTORESIST
STRIP AND RESIDUE REMOVAL
PROCESSING FOR POST ETCHING
OF LOW-K FILMS
First Named Inventor: HUONG NGUYEN
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-01-20
Effective Receipt Date: 2004-04-22
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8790
Attorney Docket Number: AMAT5735C1
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 200782
Deposit Account Name: BRIAN K. HRNA
Access Code: ****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-04-22
RAM Sequence Number: 34




Digital Certificate Holder: cn=Brian K. Hrna,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: 18f9e7968ceb74a5d3dd97d5a258f58393021419



TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	SOLVENT FREE PHOTORESIST STRIP AND RESIDUE REMOVAL PROCESSING FOR POST ETCHING OF LOW-K FILMS															
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>BRIAN K. HRNA Registered Number: 41,852</td><td>[BRIAN K. HRNA]</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	BRIAN K. HRNA Registered Number: 41,852	[BRIAN K. HRNA]	Attorney								
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Comments

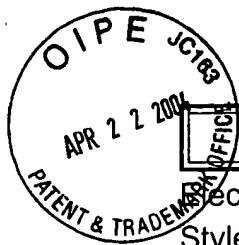


FEE TRANSMITTAL


Electronic Version v08

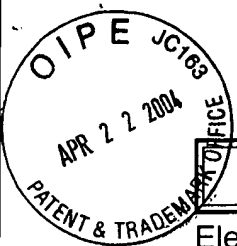
Stylesheet Version v08.0

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TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code ****											
Deposit name: MOSER PATTERSON SHERIDAN											
Deposit authorized name: BRIAN K. HRNA											
Signature: /BRIAN K. HRNA/											
Date (YYYYMMDD): 2004-04-22											

**FEE TRANSMITTAL**

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
Invention

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Application Number: 10/761122



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Search string: (6214728 or 6130166 or 6124213 or 6074569
or 6062237 or 6046115 or 6043004 or 6037255
or 6030901 or 6024045 or 5811358 or 5681780
or 5660682 or 4357203 or 4028155).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6214728	2001-04-10	CHAN, ET AL.			
	2	6130166	2001-10-10	YEH			
	3	6124213	2000-09-26	USAMI, ET AL.			
	4	6074569	2000-06-13	KIZILOGLU, ET AL.			
	5	6062237	2000-05-16	BROWN, ET AL.			
	6	6046115	2000-04-04	MOLLOY, ET AL.			
	7	6043004	2000-03-28	KURIMOTO			
	8	6037255	2000-03-14	HUSSEIN, ET AL.			
	9	6030901	2000-02-29	HOPPER, ET AL.			
	10	6024045	2000-02-15	KIKUCHI, ET AL.			
	11	5811358	1998-09-22	TSENG, ET AL.			
	12	5681780	1997-10-28	MIHARA, ET AL.			
	13	5660682	1997-08-27	ZHAO, ET AL.			
	14	4357203	1982-11-02	ZELEZ			
	15	4028155	1977-06-07	JACOB			

Signature

Examiner Name	Date